


- △1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.
- △2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- △6 Stand-off: material- Teflon; 2.16mm [0.085"] dia. 1.52mm [0.060"] thick.

Description: Prototyping adaptor

QFP 64 position (0.5mm. pitch) ZIF socket to PGA male base pattern. Add "W" to part number for optional wire wrap sub-base. Reference part number SB-PGA13/64B-01W to order additional wire wrap sub bases.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

PA-QFE64SD-P-Z-01(W) Drawing		Status: Released	Scale 2:1	Rev: C
	© 1996 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: V. Thao		Date: 9/24/96
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